

BUK78150-55A

TrenchMOS™ standard level FET

Rev. 01 — 30 January 2001

Product specification

1. Description

N-channel enhancement mode field-effect power transistor in a plastic package using TrenchMOS™¹ technology, featuring very low on-state resistance.

Product availability:
BUK78150-55A in SOT223 (SC-73).

2. Features

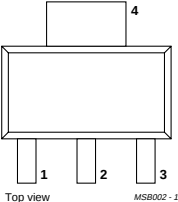
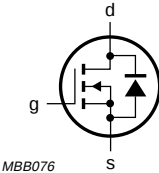
- TrenchMOS™ technology
- Q101 compliant
- 150 °C rated
- Standard level compatible.

3. Applications

- Automotive and general purpose power switching:
 - ◆ 12 V and 24 V loads
 - ◆ Motors, lamps and solenoids.

4. Pinning information

Table 1: Pinning - SOT223 (SC-73), simplified outline and symbol

Pin	Description	Simplified outline	Symbol
1	gate (g)		
2	drain (d)		
3	source (s)		
4	drain (d)		

SOT223 (SC-73)

1. TrenchMOS is a trademark of Royal Philips Electronics.



5. Quick reference data

Table 2: Quick reference data

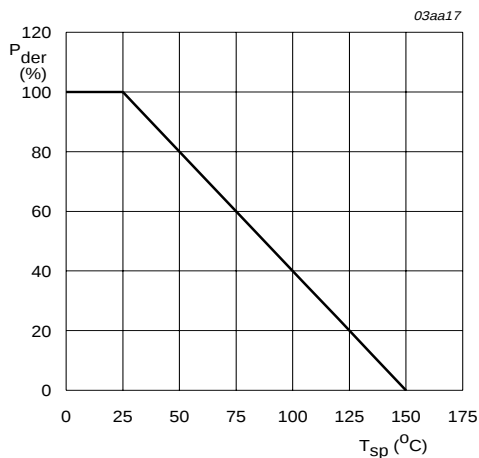
Symbol	Parameter	Conditions	Typ	Max	Unit
V_{DS}	drain-source voltage (DC)		–	55	V
I_D	drain current (DC)	$T_{sp} = 25\text{ °C}$; $V_{GS} = 10\text{ V}$	–	5.5	A
P_{tot}	total power dissipation	$T_{sp} = 25\text{ °C}$	–	8	W
T_j	junction temperature		–	150	°C
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}$; $I_D = 5\text{ A}$			
		$T_j = 25\text{ °C}$	128	150	mΩ
		$T_j = 150\text{ °C}$	–	278	mΩ

6. Limiting values

Table 3: Limiting values

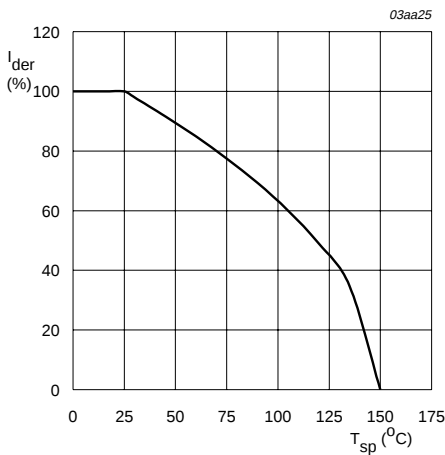
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage (DC)		–	55	V
V_{DGR}	drain-gate voltage (DC)	$R_{GS} = 20\text{ k}\Omega$	–	55	V
V_{GS}	gate-source voltage (DC)		–	±20	V
I_D	drain current (DC)	$T_{sp} = 25\text{ °C}$; $V_{GS} = 10\text{ V}$; Figure 2 and 3	–	5.5	A
		$T_{sp} = 100\text{ °C}$; $V_{GS} = 10\text{ V}$; Figure 2	–	3.8	A
I_{DM}	peak drain current	$T_{sp} = 25\text{ °C}$; pulsed; $t_p \leq 10\text{ }\mu\text{s}$; Figure 3	–	22	A
P_{tot}	total power dissipation	$T_{sp} = 25\text{ °C}$; Figure 1	–	8	W
T_{stg}	storage temperature		–55	+150	°C
T_j	operating junction temperature		–55	+150	°C
Source-drain diode					
I_{DR}	reverse drain current (DC)	$T_{sp} = 25\text{ °C}$	–	5.5	A
I_{DRM}	pulsed reverse drain current	$T_{sp} = 25\text{ °C}$; pulsed; $t_p \leq 10\text{ }\mu\text{s}$	–	22	A
Avalanche ruggedness					
W_{DSS}	non-repetitive avalanche energy	unclamped inductive load; $I_D = 5\text{ A}$; $V_{DS} \leq 55\text{ V}$; $V_{GS} = 10\text{ V}$; $R_{GS} = 50\text{ }\Omega$; starting $T_{sp} = 25\text{ °C}$	–	25	mJ



$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$

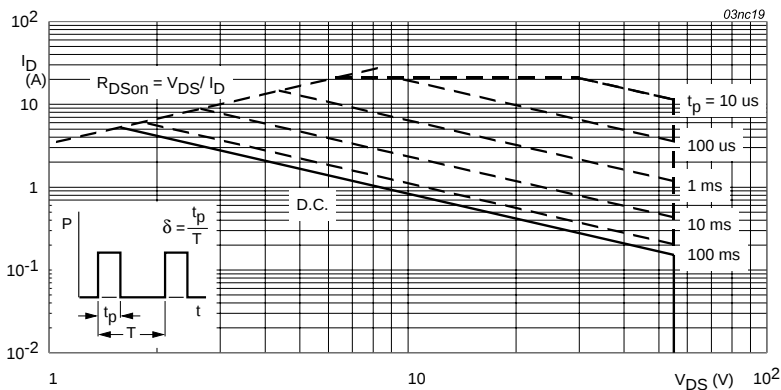
Fig 1. Normalized total power dissipation as a function of solder point temperature.



$$V_{GS} \geq 4.5 \text{ V}$$

$$I_{der} = \frac{I_D}{I_{D(25^{\circ}C)}} \times 100\%$$

Fig 2. Normalized continuous drain current as a function of solder point temperature.



$T_{amb} = 25^{\circ}C$; I_{DM} is single pulse.

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage.

7. Thermal characteristics

Table 4: Thermal characteristics

Symbol	Parameter	Conditions	Value	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	Figure 4	70	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		15	K/W

7.1 Transient thermal impedance

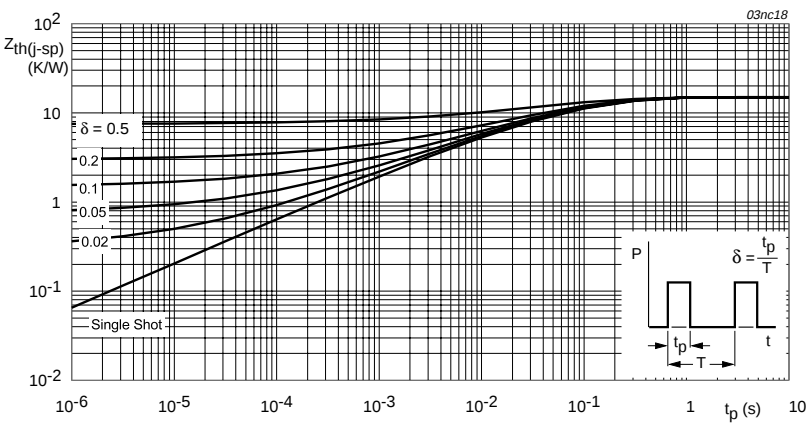


Fig 4. Transient thermal impedance from junction to solder point as a function of pulse duration.

8. Characteristics

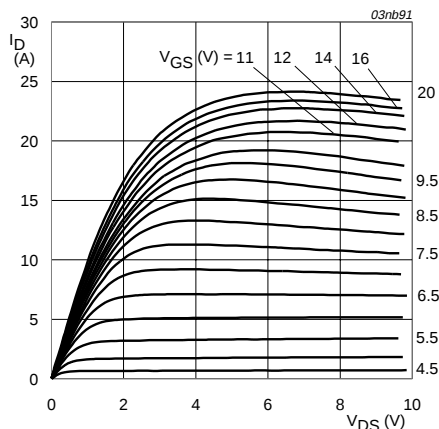
Table 5: Characteristics

$T_j = 25\text{ °C}$ unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V _{(BR)DSS}	drain-source breakdown voltage	I _D = 0.25 mA; V _{GS} = 0 V				
		T _j = 25 °C	55	–	–	V
		T _j = –55 °C	50	–	–	V
V _{GS(th)}	gate-source threshold voltage	I _D = 1 mA; V _{DS} = V _{GS} ; Figure 9				
		T _j = 25 °C	2	3	4	V
		T _j = 150 °C	1	–	–	V
		T _j = –55 °C	–	–	4.4	V
I _{DSS}	drain-source leakage current	V _{DS} = 55 V; V _{GS} = 0 V				
		T _j = 25 °C	–	0.05	10	μA
		T _j = 150 °C	–	–	500	μA
I _{GSS}	gate-source leakage current	V _{GS} = ±20 V; V _{DS} = 0 V	–	2	100	nA
R _{DSon}	drain-source on-state resistance	V _{GS} = 10 V; I _D = 5 A; Figure 7 and 8				
		T _j = 25 °C	–	128	150	mΩ
		T _j = 150 °C	–	–	278	mΩ
Dynamic characteristics						
C _{iss}	input capacitance	V _{GS} = 0 V; V _{DS} = 25 V;	–	170	230	pF
C _{oss}	output capacitance	f = 1 MHz; Figure 12	–	54	65	pF
C _{rss}	reverse transfer capacitance		–	37	52	pF
t _{d(on)}	turn-on delay time	V _{DD} = 30 V; R _L = 2.7 Ω;	–	3	–	ns
t _r	rise time	V _{GS} = 10 V; R _G = 5.6 Ω	–	26	–	ns
t _{d(off)}	turn-off delay time		–	8	–	ns
t _f	fall time		–	10	–	ns

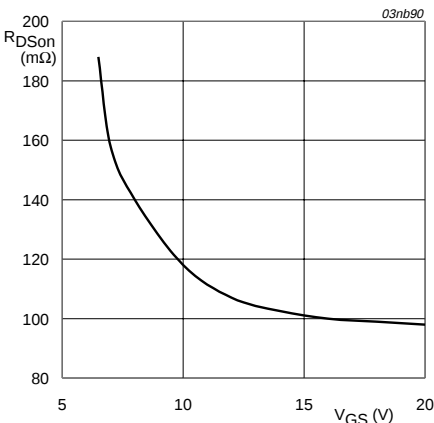
Table 5: Characteristics...continued
 $T_j = 25\text{ }^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Source-drain diode						
V_{SD}	source-drain (diode forward) voltage	$I_S = 5\text{ A}$; $V_{GS} = 0\text{ V}$; Figure 15	–	0.85	1.2	V
t_{rr}	reverse recovery time	$I_S = 10\text{ A}$; $dI_S/dt = -100\text{ A}/\mu\text{s}$	–	32	–	ns
Q_r	recovered charge	$V_{GS} = -10\text{ V}$; $V_{DS} = 30\text{ V}$	–	50	–	nC



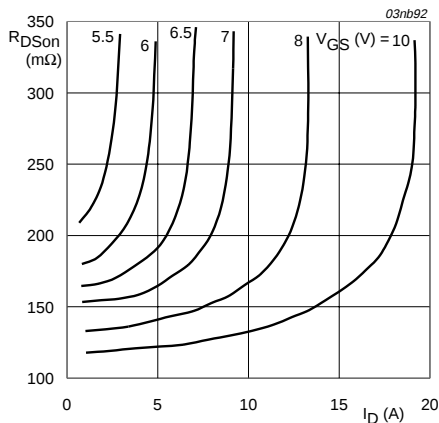
$T_j = 25\text{ }^{\circ}\text{C}$

Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values.



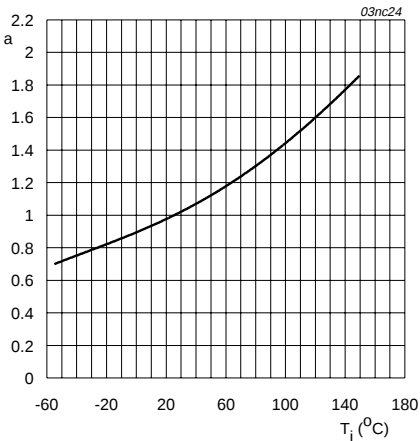
$T_j = 25\text{ }^{\circ}\text{C}$; $I_D = 5\text{ A}$

Fig 6. Drain-source on-state resistance as a function of gate-source voltage; typical values.



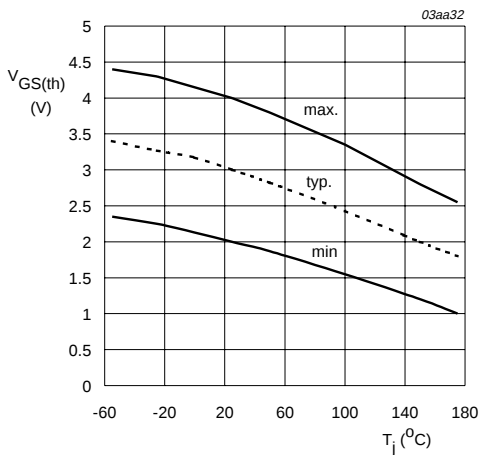
$T_j = 25\text{ }^{\circ}\text{C}$

Fig 7. Drain-source on-state resistance as a function of drain current; typical values.



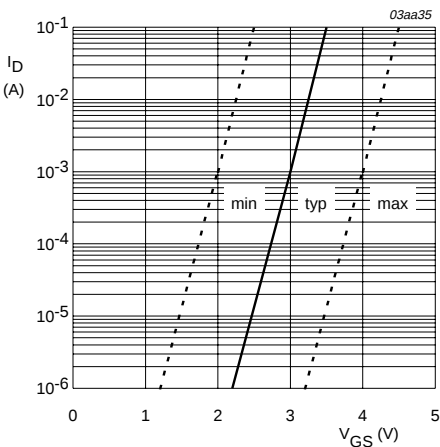
$$a = \frac{R_{DSon}}{R_{DSon(25^{\circ}\text{C})}}$$

Fig 8. Normalized drain-source on-state resistance factor as a function of junction temperature.



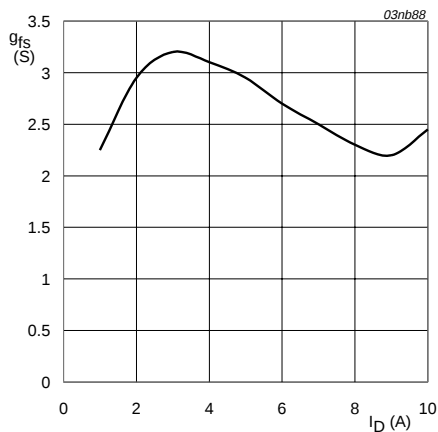
$I_D = 1 \text{ mA}$; $V_{DS} = V_{GS}$

Fig 9. Gate-source threshold voltage as a function of junction temperature.



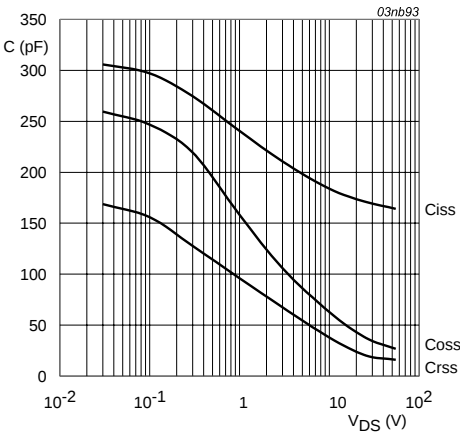
$T_j = 25 \text{ °C}$; $V_{DS} = V_{GS}$

Fig 10. Sub-threshold drain current as a function of gate-source voltage.



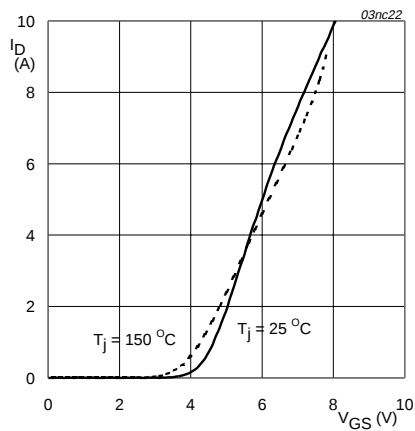
$T_j = 25 \text{ °C}$; $V_{DS} = 25 \text{ V}$

Fig 11. Forward transconductance as a function of drain current; typical values.



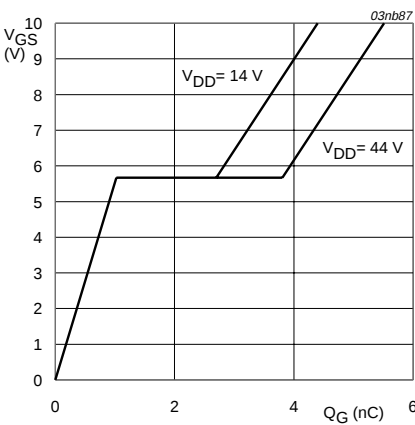
$V_{GS} = 0 \text{ V}$; $f = 1 \text{ MHz}$

Fig 12. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values.



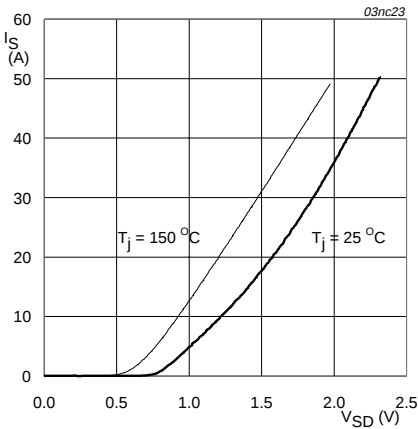
$V_{DS} = 25\text{ V}$

Fig 13. Transfer characteristics: drain current as a function of gate-source voltage; typical values.



$T_j = 25\text{ °C}; I_D = 5\text{ A}$

Fig 14. Gate-source voltage as a function of turn-on gate charge; typical values.



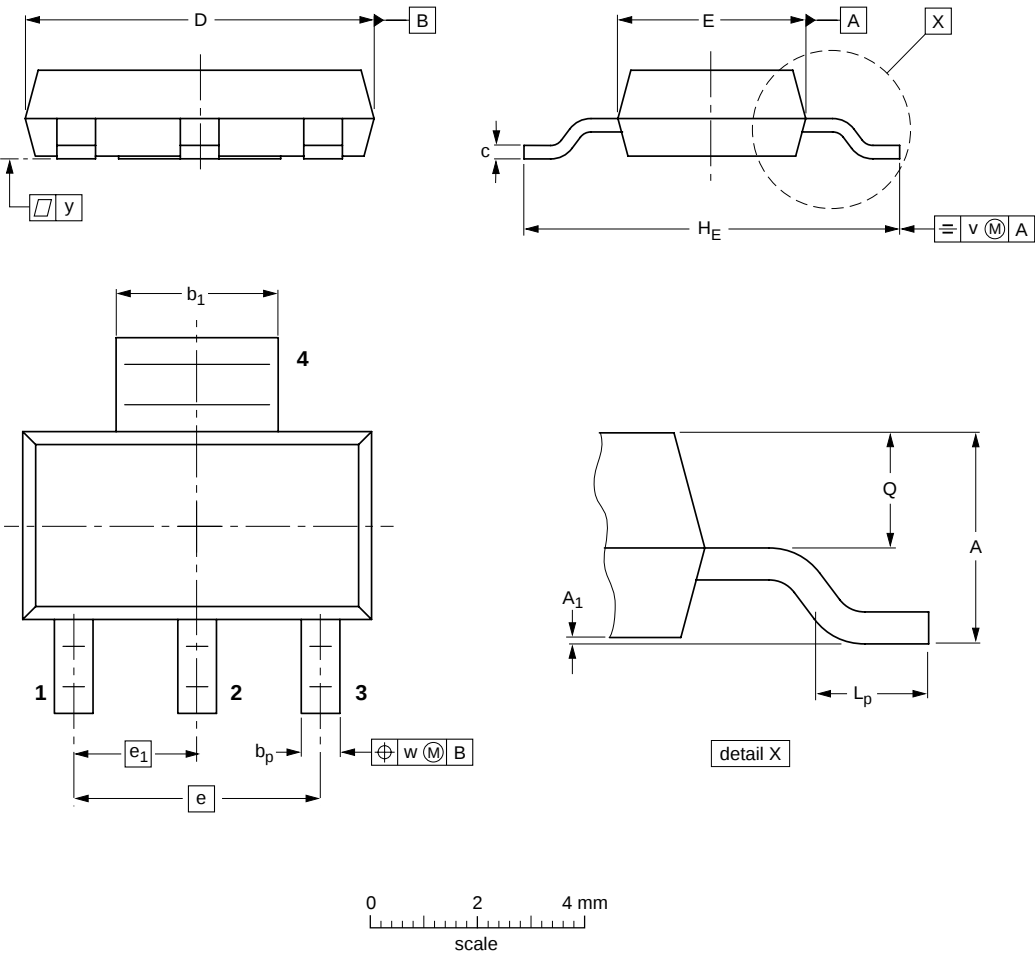
$V_{GS} = 0\text{ V}$

Fig 15. Reverse diode current as a function of reverse diode voltage; typical values.

9. Package outline

Plastic surface mounted package; collector pad for good heat transfer; 4 leads

SOT223



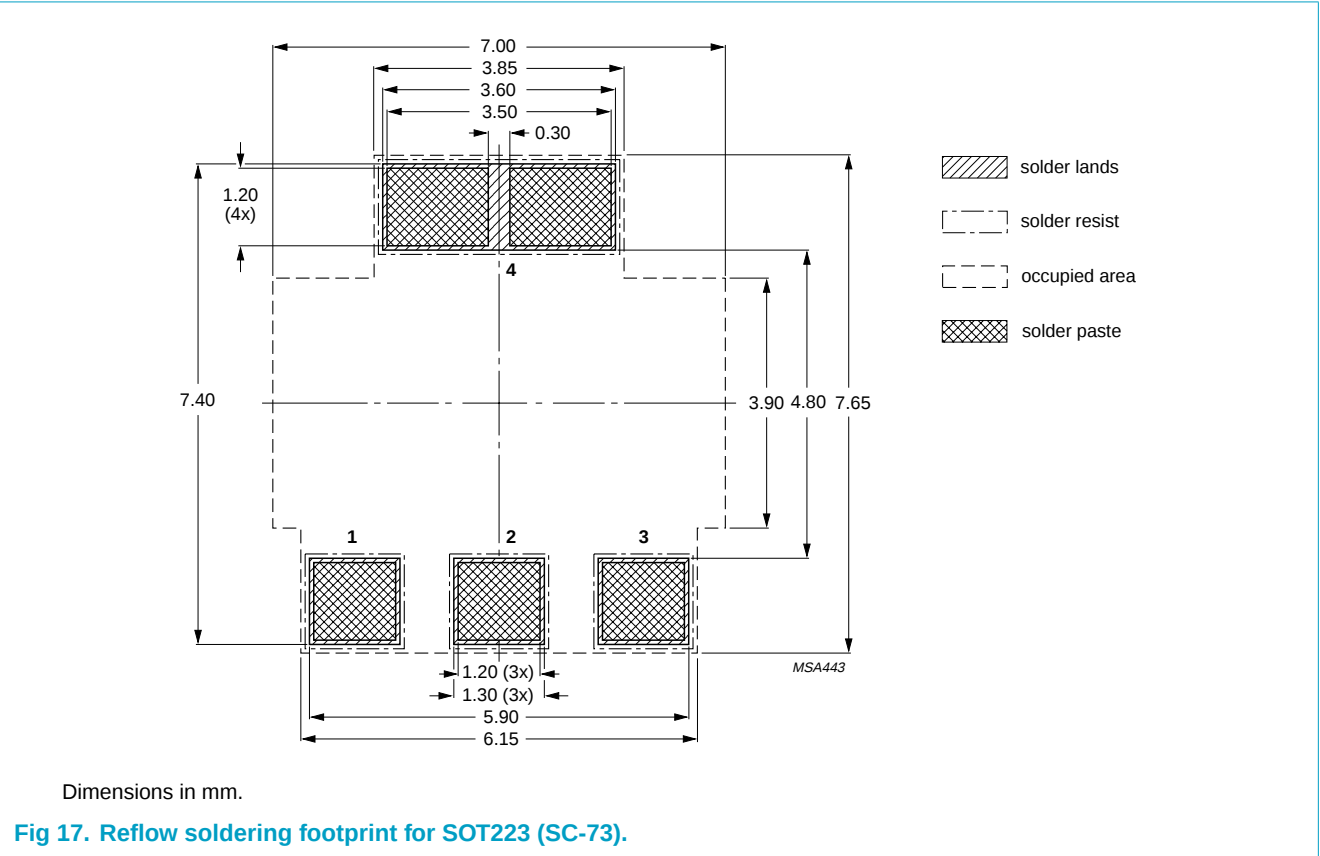
DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	b _p	b ₁	c	D	E	e	e ₁	H _E	L _p	Q	v	w	y
mm	1.8 1.5	0.10 0.01	0.80 0.60	3.1 2.9	0.32 0.22	6.7 6.3	3.7 3.3	4.6	2.3	7.3 6.7	1.1 0.7	0.95 0.85	0.2	0.1	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT223			SC-73			97-02-28 99-09-13

Fig 16. SOT223 (SC-73).

10. Soldering



11. Revision history

Table 6: Revision history

Rev	Date	CPCN	Description
01	20010130	-	Product specification; initial version.

12. Data sheet status

Datasheet status	Product status	Definition ^[1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued data sheet before initiating or completing a design.

13. Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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(SCA71)

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